

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Andrews et al. Serial No.: 10/733,845 Confirmation: 9026 Group Art Unit: 2812

Filed: December 11, 2003

SEMICONDUCTOR SUBSTRATE ASSEMBLIES AND METHODS FOR

PREPARING AND DICING THE SAME

Date: May 27, 2004

Mail Stop Missing Parts Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

# REQUEST FOR CORRECTED FILING RECEIPT

Sir:

For:

In reviewing the filing receipt (copy attached) for the above referenced application, Attorney for Applicants notes that the title reads, "Semiconductor substrate assemblies and method for preparing and dicing the same". However, as indicated on the Application, the title should read, "Semiconductor substrate assemblies and methods for preparing and dicing the same".

Additionally, Applicants previously submitted a Petition to Accord Proper Filing Date to correct the filing date to December 11, 2003 on May 5, 2004. Applicants respectfully request that a corrected filing receipt be issued to reflect the corrected title and filing date.

Respectfully submitted,

David D. Beatty

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#### **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Missing Parts, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on May 27, 2004.

Katie A. Chung





UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.C. Dox 1450 Alexandris, Vignis 22313-1450 www.usplo.gov

FILING OR 371 FIL FEE REC'D APPL NO. ART UNIT ATTY.DOCKET NO DRAWINGS TOT CLMS IND CLMS (c) DATE 0.00 10/733,845 12/12/2003 2812 5308-299 15 59 4 MYERS BIGEL Ε **CONFIRMATION NO. 9026** Myers Bigel Sibley & Sajovec, P.A. **FILING RECEIPT** P.O. Box 37428 Raleigh, NC 27627 OC000000012263239

Date Mailed: 04/05/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

#### Applicant(s)

Peter Andrews, Durham, NC; Elbert Brown, Morrisville, NC; Gerry Negley, Hillsborough, NC;

Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted: 04/02/2004

Projected Publication Date: To Be Determined - pending completion of Missing Parts

Non-Publication Request: No

Early Publication Request: No

04-07-04 A98:47 IN

Title

Semiconductor substrate assemblies and method for preparing and dicing the same

**Preliminary Class** 

438

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